

	Hit s	Search Text	DBs
21	58	((print\$4 near9 (wiring or circuit\$4) near9 board) or PCB or ((circuit\$4 or wiring) near9 board))) and (((barium near9 titanate) or BaTiO\$2) same (coarse or particle) same (size or diameter)) and (((barium near9 titanate) or BaTiO\$3) same (epoxy or polymer or PTFE or (thermosetting near9 resin) or resin\$4) same particle same (diameter or micron or nanometer or nm))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
22	30	((print\$4 near9 (wiring or circuit\$4) near9 board) or PC B or ((circuit\$4 or wiring) near9 board))) and (((barium near9 titanate) or BaTiO\$2) same (coarse or particle) same (size or diameter)) and (((barium near9 titanate) or BaTiO\$3) same (epoxy or polymer or PTFE or (thermosetting near9 resin) or resin\$4)) and capacitor and (electrode same (top or bottom))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Hit s	Search Text	DBs
23	50	((print\$4 near9 (wiring or circuit\$4) near9 board) or PCB or ((circuit\$4 or wiring) near9 board)) and (((barium near9 titanate) or BaTiO\$2) same (coarse or particle) same (size or diameter)) and (((barium near9 titanate) or BaTiO\$3) same (epoxy or polymer or PTFE or (thermosetting near9 resin) or resin\$4)) and capacitor and ((electrode or conductive or metal\$4) same (top or bottom)) and ((resin or epoxy) same (copper or metal\$4 or Cu))	US - PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
24	153	((print\$4 near9 (wiring or circuit\$4) near9 board) or PCB or ((circuit\$4 or wiring) near9 board)) and ((fill\$4 or filler or paste) same (via or hole or trench or through\$4hole) same contact\$4 same electrode same capacitor)	US - PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
25	12	((print\$4 near9 (wiring or circuit\$4) near9 board) or PCB or ((circuit\$4 or wiring) near9 board)) and (((fill\$4 or deposit\$4) near26 (via or hole or trench or through\$4hole) near9 (capacit\$4 or dielectric or (capacit\$4 near9 (paste or material)))) same contact\$4 same bottom same top same electrode same capacitor)	US - PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

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26	8	((print\$4 near9 (wiring or circuit\$4) near9 board) or PCB or ((circuit\$4 or wiring) near9 board))) and (((fill\$4 or deposit\$4) near26 (via or hole or through\$4hole) near9 (capacit\$4 or dielectric or (capacit\$4 near9 (paste or material)))) same contact\$4 same bottom same top same electrode)	US-PPGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
27	23	((print\$4 near9 (wiring or circuit\$4) near9 board) or PCB or ((circuit\$4 or wiring) near9 board))) and (((fill\$4 or deposit\$4 or embed \$5) near26 (via or hole or through\$4hole or wiring\$4board or CPC or board) near9 (capacit\$4 or dielectric or ((capacit\$4 or inorganic or resin) near9 (paste or material)))) same contact\$4 same bottom same top same electrode)	US-PPGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
28	13	((print\$4 near9 (wiring or circuit\$4) near9 board) or PCB or ((circuit\$4 or wiring) near9 board)) near29 (dielectric or non\$4copper)) and (((fill\$4 or deposit\$4 or embed\$5) near26 (via or hole or through\$4hole or wiring\$4board or CPC or board) near9 (capacit\$4 or dielectric or ((capacit\$4 or inorganic or resin) near9 (paste or material)))) same contact\$4 same bottom same top same electrode)	US-PPGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB